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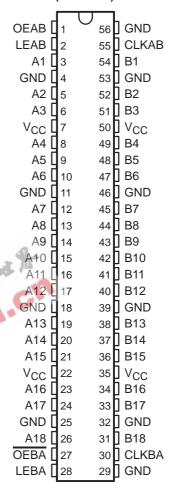
- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- UBT[™] (Universal Bus Transceiver)
 Combines D-Type Latches and D-Type
 Flip-Flops for Operation in Transparent,
 Latched, or Clocked Mode
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 5 V, T_A = 25°C
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

These 18-bit universal bus transceivers consist of storage elements that can operate either as D-type latches or D-type flip-flops to allow data flow in transparent or clocked modes.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. When OEAB is high, the outputs are active. When OEAB is low, the outputs are in the high-impedance state.

SN54ABT16501 . . . WD PACKAGE SN74ABT16501 . . . DGG OR DL PACKAGE (TOP VIEW)



Data flow for B to A is similar to that of A to B but uses $\overline{\text{OEBA}}$, LEBA, and CLKBA. The output enables are complementary (OEAB is active high and $\overline{\text{OEBA}}$ is active low).

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor and $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sourcing/current-sinking capability of the driver.



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description (continued)

The SN54ABT16501 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ABT16501 is characterized for operation from -40° C to 85°C.

FUNCTION TABLE†

	INPUTS						
OEAB	LEAB	CLKAB	Α	В			
L	Х	Х	Х	Z			
Н	Н	Χ	L	L			
Н	Н	Χ	Н	Н			
Н	L	\uparrow	L	L			
Н	L	\uparrow	Н	Н			
Н	L	Н	Χ	в ₀ ‡ в ₀ §			
Н	L	L	Χ	В ₀ §			

[†] A-to-B data flow is shown: B-to-A flow is similar but uses $\overline{\mathsf{OEBA}}$, LEBA, and CLKBA.

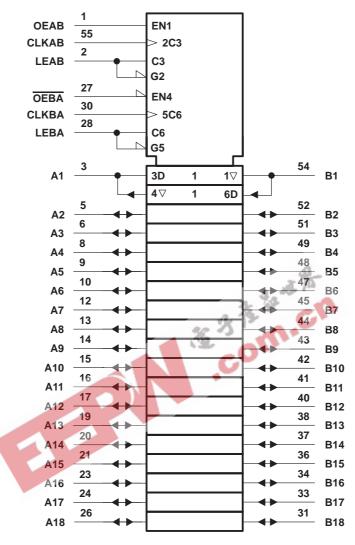


[‡]Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low

was high before LEAB went low

§ Output level before the indicated steady-state input conditions were established

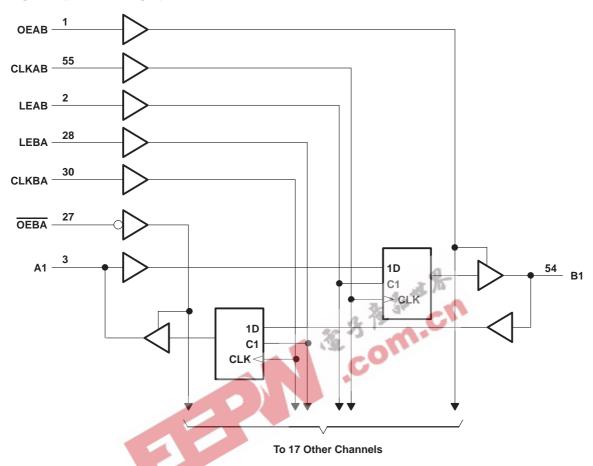
logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16501	96 mA
SN74ABT16501	128 mA
Input clamp current, $I_{ K }(V_1 < 0)$	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stg}	−65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



SN54ABT16501, SN74ABT16501 18-BIT UNIVERSAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS SCBS086C - FEBRUARY 1991 - REVISED JANUARY 1997

recommended operating conditions (see Note 3)

				16501	SN74ABT16501		UNIT
			MIN	MAX	MIN	MAX	UNIT
V _{CC} Supply voltage				5.5	4.5	5.5	V
V _{IH} High-level input voltage			2	EN	2		V
VIL	V _{IL} Low-level input voltage					0.8	V
٧ _I	V _I Input voltage				0	VCC	V
ІОН	IOH High-level output current					-32	mA
lOL	L Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	72	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Т	_A = 25°C	;	SN54ABT16501		SN74ABT16501		UNIT	
PAI	KAWETEK	l lesi coi	NDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/a		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
V _{OL}		V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.55		0.55			V	
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55*				0.55	V	
V_{hys}	_				100			4			mV	
ΙΙ	Control inputs	$V_{CC} = 5.5 \text{ V},$	$V_I = V_{CC}$ or GND			±1		<u>#</u> 1		±1	μΑ	
	A or B ports	VCC = 0.0 V,	V1 = VCC or GIVE			±100		±100		±100	μπ	
l _{OZH} ‡		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			50		50		50	μΑ	
lozL [‡]		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50	S	-50		-50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	30/0	•		±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high		.0.	50		50		50	μΑ	
ΙΟ§		$V_{CC} = 5.5 \text{ V},$	V _O = 2.5 V	-50	-100	-180	- 50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high		Car.	3		5		3		
ICC	A or B ports $I_O = 0$,	$I_{O} = 0$,	Outputs low		C	76		76		76	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			3.3		5.3		3.3		
A1 ¶	Control inputs	V _{CC} = 5.5 V, One i				5		6		5	mA	
∆ICC¶	A or B ports	Other inputs at VC	c or GND			1.5		1.5		1.5	111/	
Ci	Control inputs	$V_1 = 2.5 \text{ V or } 0.5 \text{ V}$			4						pF	
C _{io}	A or B ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$	1		8						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54AB	Γ16501	SN74AB1	Γ16501	UNIT
				MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency, CLKAB or	0	105	0	105	MHz		
. #	Pulse duration	LEAB or LEBA high		3.3	EN	3.3		
t _W #	Fulse duration	CLKAB or CLKBA high or low	4.7	FL	4.7		ns	
		A before CLKAB↑ or B before CLKBAˆ	4 4	2	3.5			
t _{su}	Setup time	A before LEAB↓ or B before LEBA↓ CLK high		4		4		ns
				1,5		1.5		
. .	Hold time	A after CLKAB↑ or B after CLKBA↑		& 1		1		ns
th th	HOIG UITIE	A after LEAB↓ or B after LEBA↓	2.5		2.5		115	

[#]This parameter is specified by design, but not production tested.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters IOZH and IOZL include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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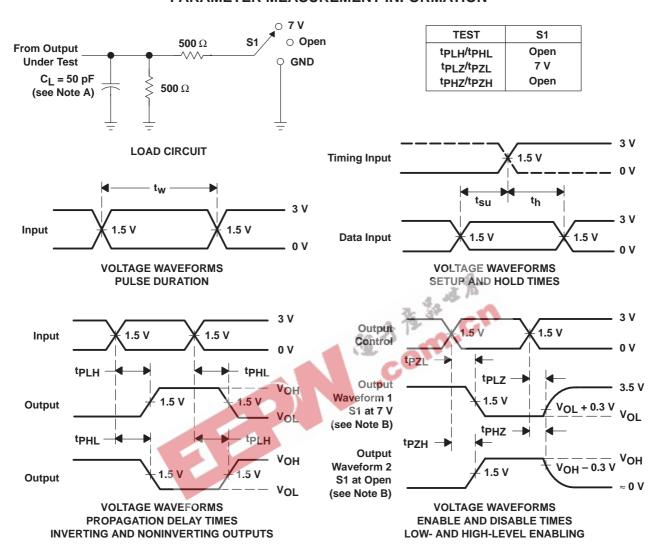
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V 4 = 25°C	/, ;	SN54AB1	T16501	SN74AB1	Γ16501	UNIT
	(INFOT)	(001-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
fmax	CLKAB or CLKBA		105	160		105		105		MHz
t _{PLH}	A or B	B or A	1	2.6	3.4	1	3.9	1	3.7	ns
t _{PHL}		BULA	1	2.6	3.4	1	4.1	1	4	115
t _{PLH}	LEAB or LEBA	B or A	1.3	3.3	4.3	1.3	5.4	1.3	5.1	ns
t _{PHL}	LEAD OF LEDA	BULK	1.4	3.1	4.1	1.4	4.6	1.4	4.4	115
t _{PLH}	CLKAB or CLKBA	B or A	1.5	3.5	4.5	1.5	5.3	1.5	5	ns
t _{PHL}	CLRAB OF CLRBA	BULA	1.3	3.1	4.1	1.3	4.6	1.3	4.4	115
^t PZH	OEAB or OEBA	B or A	1	3	4	1	4.8	1	4.7	ns
t _{PZL}	OEAB OF OEBA	BOIA	2.6	4.9	5.9	2.6	6.6	2.6	6.5	115
^t PHZ	OEAB or OEBA	B or A	1.6	3.9	4.9	1.6	5.9	1.6	5.8	ns
t _{PLZ}	OEAD OF OEDA	BUIA	1.1	3.4	4.4	1.1	5.1	1.1	4.9	115



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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